

Title (en)
AGGLOMERATED BORON NITRIDE PARTICLES, COMPOSITION CONTAINING SAID PARTICLES, AND THREE-DIMENSIONAL INTEGRATED CIRCUIT HAVING LAYER COMPRISING SAID COMPOSITION

Title (de)
AGGLOMERIERTE BORNITRIDPARTIKEL, ZUSAMMENSETZUNG MIT DEN BESAGTEN PARTIKELN UND DREIDIMENSIONALER INTEGRIERTER SCHALTKEIS MIT SCHICHT MIT DER BESAGTEN ZUSAMMENSETZUNG

Title (fr)
PARTICULES DE NITRURE DE BORE AGGLOMÉRÉES, COMPOSITION CONTENANT LESDITES PARTICULES, ET CIRCUIT INTÉGRÉ TRIDIMENSIONNEL DOTÉ D'UNE COUCHE COMPRENANT LADITE COMPOSITION

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Application
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Abstract (en)
[origin: EP2786961A1] To provide a composition for a three-dimensional integrated circuit capable of forming a filling interlayer excellent in thermal conductivity also in a thickness direction, using agglomerated boron nitride particles excellent in the isotropy of thermal conductivity, disintegration resistance and kneading property with a resin. A composition for a three-dimensional integrated circuit, comprising agglomerated boron nitride particles which have a specific surface area of at least 10 m²/g, the surface of which is constituted by boron nitride primary particles having an average particle size of at least 0.05 µm and at most 1 µm, and which are spherical, and a resin (A) having a melt viscosity at 120 °C of at most 100 Pa.s.

IPC 8 full level
C01B 21/064 (2006.01); **C01B 35/14** (2006.01); **C08G 59/40** (2006.01); **C08K 3/38** (2006.01); **C08L 63/00** (2006.01); **C08L 101/00** (2006.01); **C09D 201/00** (2006.01); **C09K 5/14** (2006.01); **H01L 21/77** (2017.01); **H01L 23/00** (2006.01); **H01L 27/04** (2006.01)

CPC (source: CN EP KR US)
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